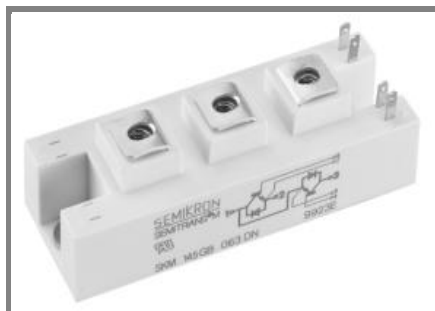


# SKM 195GB126DN



**SEMITRANS™ 2N**

## Trench IGBT Module

**SKM 195GB126DN**

**SKM 195GAL126DN**

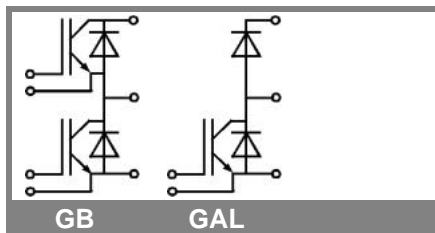
Preliminary Data

### Features

- Homogeneous Si
- Trench = Trenchgate technology
- $V_{CEsat}$  with positive temperature coefficient
- High short circuit capability, self limiting to  $6 \times I_C$

### Typical Applications

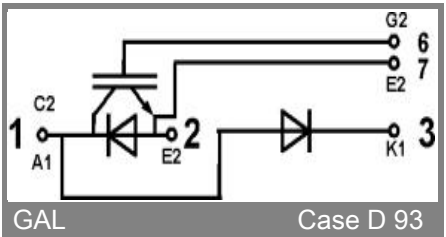
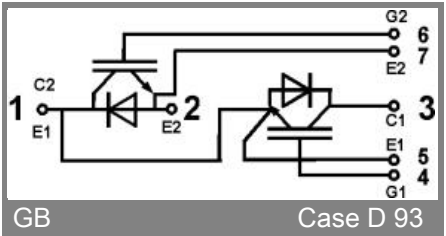
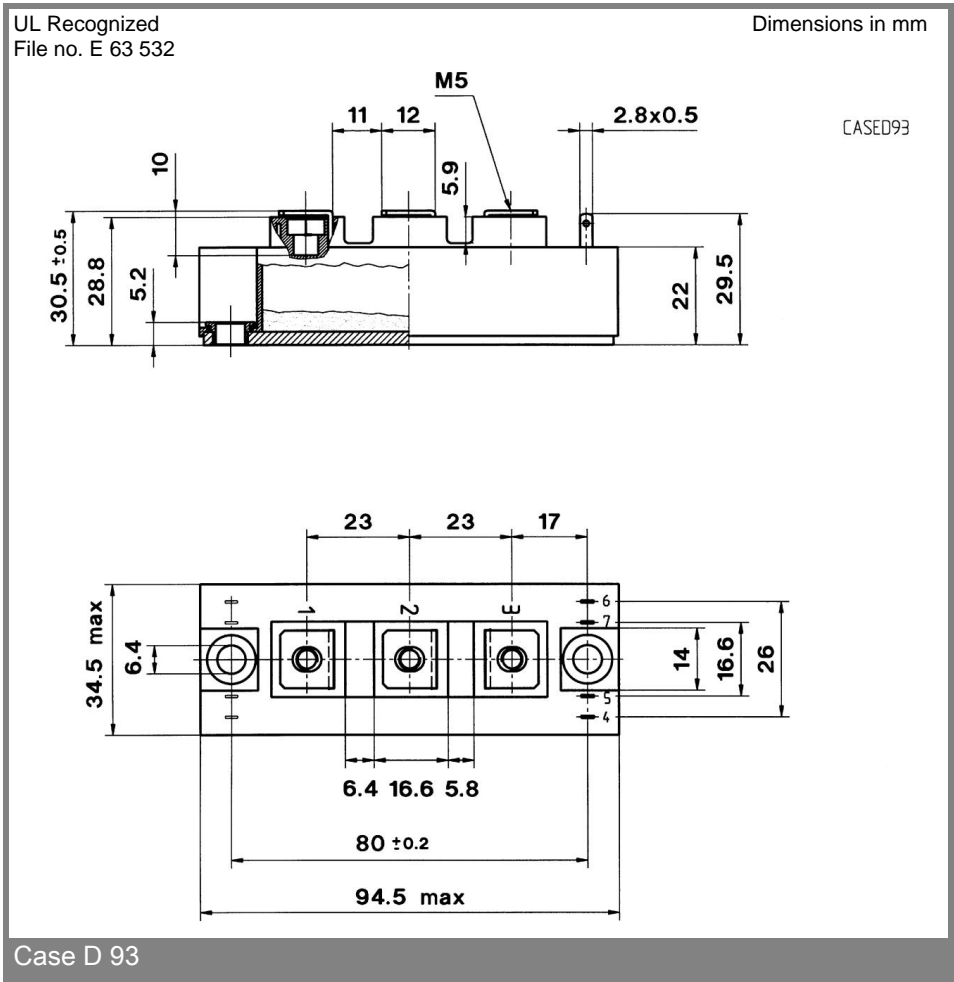
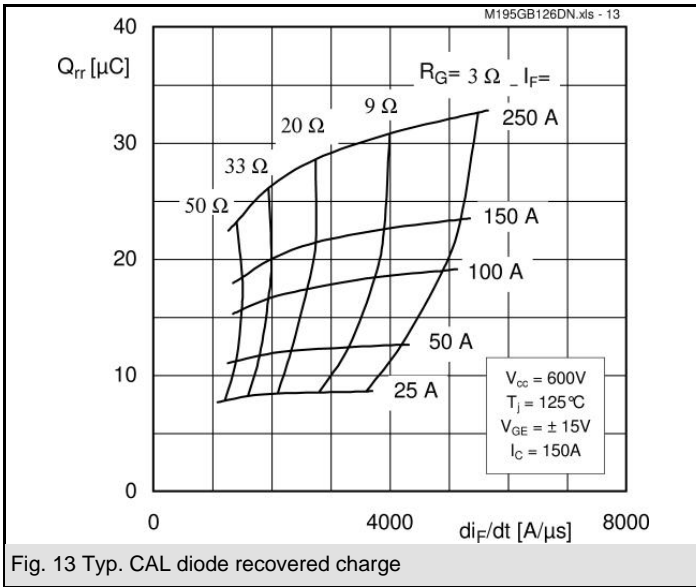
- AC inverter drives
- UPS
- Electronic welders



Absolute Maximum Ratings		$T_c = 25\text{ °C}$ , unless otherwise specified	
Symbol	Conditions	Values	Units
<b>IGBT</b>			
$V_{CES}$		1200	V
$I_C$	$T_c = 25\text{ (80) °C}$	220 (160)	A
$I_{CRM}$	$t_p = 1\text{ ms}$	300	A
$V_{GES}$		$\pm 20$	V
$T_{vj}$ ( $T_{stg}$ )	$T_{OPERATION} \leq T_{stg}$	- 40 ... + 150 (125)	°C
$V_{isol}$	AC, 1 min.	4000	V
<b>Inverse diode</b>			
$I_F$	$T_c = 25\text{ (80) °C}$	200 (160)	A
$I_{FRM}$	$t_p = 1\text{ ms}$	300	A
$I_{FSM}$	$t_p = 10\text{ ms; sin.; } T_j = 150\text{ °C}$	1450	A
<b>Freewheeling diode</b>			
$I_F$	$T_c = 25\text{ (80) °C}$	200 (160)	A
$I_{FRM}$	$T_c = 25\text{ (80) °C, } t_p = 1\text{ ms}$	440 (320)	A
$I_{FSM}$	$t_p = 10\text{ ms; sin.; } T_j = 150\text{ °C}$	1450	A

Characteristics		$T_c = 25\text{ °C}$ , unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units
<b>IGBT</b>					
$V_{GE(th)}$	$V_{GE} = V_{CE}, I_C = 6\text{ mA}$	5	5,8	6,5	V
$I_{CES}$	$V_{GE} = 0, V_{CE} = V_{CES}, T_j = 25\text{ (125) °C}$		0,2	0,6	mA
$V_{CE(TO)}$	$T_j = 25\text{ (125) °C}$		1 (0,9)	1,15	V
$r_{CE}$	$V_{GE} = 15\text{ V, } T_j = 25\text{ (125) °C}$		4,7 (7,3)	6,7	mΩ
$V_{CE(sat)}$	$I_C = 150\text{ A, } V_{GE} = 15\text{ V, chip level}$		1,7 (2)	2,15	V
$C_{ies}$	under following conditions		10,5		nF
$C_{oes}$	$V_{GE} = 0, V_{CE} = 25\text{ V, } f = 1\text{ MHz}$		0,9		nF
$C_{res}$			0,8		nF
$L_{CE}$				25	nH
$R_{CC'+EE'}$	res., terminal-chip $T_c = 25\text{ (125) °C}$		0,75 (1)		mΩ
$t_{d(on)}$	$V_{CC} = 600\text{ V, } I_C = 150\text{ A}$		300		ns
$t_r$	$R_{Gon} = R_{Goff} = 5\text{ Ω, } T_j = 125\text{ °C}$		40		ns
$t_{d(off)}$	$V_{GE} = \pm 15\text{ V}$		560		ns
$t_f$			100		ns
$E_{on} (E_{off})$			16 (21)		mJ
<b>Inverse diode</b>					
$V_F = V_{EC}$	$I_F = 150\text{ A; } V_{GE} = 0\text{ V; } T_j = 25\text{ (125) °C}$		1,6 (1,6)	1,8 (1,8)	V
$V_{(TO)}$	$T_j = 25\text{ (125) °C}$		1 (0,8)	1,1 (0,9)	V
$r_T$	$T_j = 25\text{ (125) °C}$		4 (5,3)	4,7 (6)	mΩ
$I_{RRM}$	$I_F = 150\text{ A; } T_j = 125\text{ ( ) °C}$		200		A
$Q_{rr}$	$di/dt = 2000\text{ A/}\mu\text{s}$		33		μC
$E_{rr}$	$V_{GE} = 0\text{ V}$		14,5		mJ
<b>FWD</b>					
$V_F = V_{EC}$	$I_F = 150\text{ A; } V_{GE} = 0\text{ V, } T_j = 25\text{ (125) °C}$		1,6 (1,6)	1,8 (1,8)	V
$V_{(TO)}$	$T_j = 25\text{ (125) °C}$		1 (0,8)	1,1 (0,9)	V
$r_T$	$T_j = 25\text{ (125) °C}$		4 (5,3)	4,7 (6)	mΩ
$I_{RRM}$	$I_F = 150\text{ A; } T_j = 125\text{ ( ) °C}$		200		A
$Q_{rr}$	$di/dt = 2000\text{ A/}\mu\text{s}$		33		μC
$E_{rr}$	$V_{GE} = 0\text{ V}$		14,5		mJ
<b>Thermal characteristics</b>					
$R_{th(j-c)}$	per IGBT			0,16	K/W
$R_{th(j-c)D}$	per Inverse Diode			0,32	K/W
$R_{th(j-c)FD}$	per FWD			0,32	K/W
$R_{th(c-s)}$	per module			0,05	K/W
<b>Mechanical data</b>					
$M_s$	to heatsink M6	3		5	Nm
$M_t$	to terminals M5	2,5		5	Nm
w				160	g

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This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.